EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	570	L4 and @pd>="20090301"	US-PGPUB; USPAT	OR	ON	2009/10/12 09:45
L4	10113	L1 L2 L3	US-PGPUB; USPAT	OR	ON	2009/10/12 09:45
L3	5492	356/237.1-237.6.ccls.	US-PGPUB; USPAT	OR	ON	2009/10/12 09:45
L2	1033	348/86,87,125,126.ccls.	US-PGPUB; USPAT	OR	ON	2009/10/12 09:45
L1	4594	382/141,143-152.ccls.	US-PGPUB; USPAT	OR	ON	2009/10/12 09:45
S83	18	(CMP (chemical near2 mechanical near2 planarization)) near5 (while during) near5 imag$4	US-PGPUB; USPAT	OR	ON	2009/10/10 13:07
S82	23	S81 and @ad<"20000430"	US-PGPUB; USPAT	OR	ON	2009/10/10 13:02
S81	176	S80 and (rotat$4)	US-PGPUB; USPAT	OR	ON	2009/10/10 13:01
S80	313	S79 and (imag$4 same thick$5)	US-PGPUB; USPAT	OR	ON	2009/10/10 13:00
S79	1088	S78 and ((camera ccd imag$4) near10 laser)	US-PGPUB; USPAT	OR	ON	2009/10/10 12:59
S78	82972	(CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/10 12:59
S77	1	"6186877".pn.	US-PGPUB; USPAT	OR	ON	2009/10/08 17:34
S76	20	S75 and (imag$4 near5 (while dur$4) near5 (rotat $4))	US-PGPUB; USPAT	OR	ON	2009/10/08 17:08
S75	82972	(CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 17:08
S74	23	S73 and (imag$4)	US-PGPUB; USPAT	OR	ON	2009/10/08 16:55
S73	78	S72 and @ad<"20000430"	US-PGPUB; USPAT	OR	ON	2009/10/08 16:55
S72	497	S71 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 16:55

S71	15168	((speed velocit$4) near5 (object substrate semiconductor wafer die) near5 (motion moving movement))	US-PGPUB; USPAT	OR	ON	2009/10/08 16:55
S70	23	S61 and (high near3 speed near3 (imag$4 camera ccd))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:14
S69	6	S68 and (imag$4 near10 (film layer near5 (thick$5)))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:12
S68	334	S60 and (CMP (chemical near2 mechanical near2 planarization) same imag$4). ab.	US-PGPUB; USPAT	OR	ON	2009/10/08 14:12
S67	134	S66 and (imag$4 near10 (film layer near5 (thick$5)))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:11
S66	2455	S60 and (CMP (chemical near2 mechanical near2 planarization) same imag$4)	US-PGPUB; USPAT	OR	ON	2009/10/08 14:11
S65	11	S60 and ((CMP (chemical near2 mechanical near2 planarization)) same (imag $4 near10 (film layer near5 (thick$5))))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:09
S64	134	S61 and (imag$4 near10 (film layer near5 (thick$5)))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:03
S63	64	S61 and S62	US-PGPUB; USPAT	OR	ON	2009/10/08 14:02
S62	42435	(imag$4 near10 (thickness))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:02
S61	2482	S60 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:01
S60	15487	((rotat$4 RPM) near5 (speed velocit$4) near5 (object substrate semiconductor wafer die))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:01
S59	1	"6159073".pn.	US-PGPUB; USPAT	OR	ON	2009/10/08 13:36
S58	1	"5738574".pn.	US-PGPUB; USPAT	OR	ON	2009/10/08 13:21
S57	30	S55 and S56	US-PGPUB; USPAT	OR	ON	2009/10/08 13:12
S56	141526	((speed velocit$4) near5 (object substrate semiconductor wafer die))	US-PGPUB; USPAT	OR	ON	2009/10/08 13:12
S55	50	("5640242").URPN.	USPAT	OR	ON	2009/10/08 13:09

S54	6	("5333049" | "5409538" | "5413941" | "5436725" | "5452953" | "5486701").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/08 13:09
S53	1	"5640242".pn.	US-PGPUB; USPAT	OR	ON	2009/10/08 13:09
S52	10	S51 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 13:01
S51	249	(linea$3 near5 (speed velocit$4) near5 (object substrate semiconductor wafer die)) same ((imag$4 video frame))	US-PGPUB; USPAT	OR	ON	2009/10/08 13:01
S50	6	(linea$3 near5 (speed velocit$4) near5 (object substrate semiconductor wafer die)) same ((imag$4 video frame) near5 rate)	US-PGPUB; USPAT	OR	ON	2009/10/08 12:58
S49	251	S48 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:57
S48	2390	(linea$3 near5 (speed velocit$4) near5 (object substrate semiconductor wafer die))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:56
S47	78	S46 and @ad<"20000430"	US-PGPUB; USPAT	OR	ON	2009/10/08 12:55
S46	497	S45 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:55
S45	15168	((speed velocit$4) near5 (object substrate semiconductor wafer die) near5 (motion moving movement))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:54
S44	40	S43 and @ad<"20000430"	US-PGPUB; USPAT	OR	ON	2009/10/08 12:51
S43	240	S40 and ((thick$5 dimension) near5 (measur$6 determin$6) near5 (imag$4 frame))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:51
S42	218	S40 and ((thick$5 dimension) near5 (measur$6 determin$6) near5 (image frame))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:50
S41	868	S40 and ((thick$5 dimension) near5 (measur$6 determin$6))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:50

S40	7476	((speed velocit$4) near5 (object substrate semiconductor wafer die)) near10 (imag$4 video$4)	US-PGPUB; USPAT	OR	ON	2009/10/08 12:49
S39	33	S38 and ((speed velocit$4) near5 (object substrate semiconductor wafer die))	US-PGPUB; USPAT	OR	ON	2009/10/07 15:44
S38	99	S26 S27 S28 S29 S30 S31 S32 S33 S34 S35 S36	US-PGPUB; USPAT	OR	ON	2009/10/07 15:34
S37	10	US-5795495-$.DID. OR US-5861055-$.DID. OR US-5865666-$.DID. OR US-5868608-$.DID. OR US-5882244-$.DID. OR US-5888120-$.DID. OR US-5893756-$.DID. OR US-5931719-$.DID. OR US-5948697-$.DID. OR US-5957757-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:29
S36	10	US-5795495-$.DID. OR US-5861055-$.DID. OR US-5865666-$.DID. OR US-5868608-$.DID. OR US-5882244-$.DID. OR US-5888120-$.DID. OR US-5893756-$.DID. OR US-5931719-$.DID. OR US-5948697-$.DID. OR US-5957757-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:29
S35	11	US-5722875-$.DID. OR US-5722877-$.DID. OR US-5725417-$.DID. OR US-5736462-$.DID. OR US-5738567-$.DID. OR US-5741171-$.DID. OR US-5747380-$.DID. OR US-5755614-$.DID. OR US-5762536-$.DID. OR US-5762537-$.DID. OR US-5777739-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:28
S34	11	US-5691253-$.DID. OR US-5695660-$.DID. OR US-5700180-$.DID. OR US-5702292-$.DID. OR US-5704987-$.DID. OR US-5705320-$.DID. OR US-5705435-$.DID. OR US-5710076-$.DID. OR US-5712185-$.DID. OR US-5716873-$.DID. OR US-5720845-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:28

S33	11	US-5660672-$.DID. OR US-5663101-$.DID. OR US-5663797-$.DID. OR US-5664987-$.DID. OR US-5667424-$.DID. OR US-5667433-$.DID. OR US-5667629-$.DID. OR US-5668063-$.DID. OR US-5670410-$.DID. OR US-5672091-$.DID. OR US-5674784-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:27
S32	11	US-5626715-$.DID. OR US-5627110-$.DID. OR US-5637185-$.DID. OR US-5639388-$.DID. OR US-5643046-$.DID. OR US-5643050-$.DID. OR US-5644221-$.DID. OR US-5645682-$.DID. OR US-5647952-$.DID. OR US-5656229-$.DID. OR US-5658183-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:26
S31	11	US-5492594-$.DID. OR US-5516400-$.DID. OR US-5531861-$.DID. OR US-5559428-$.DID. OR US-5561541-$.DID. OR US-5595526-$.DID. OR US-5597442-$.DID. OR US-5597590-$.DID. OR US-5609511-$.DID. OR US-5614446-$.DID. OR US-5624304-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:25
S30	11	US-5321304-$.DID. OR US-5337015-$.DID. OR US-5362669-$.DID. OR US-5385866-$.DID. OR US-5389194-$.DID. OR US-5399234-$.DID. OR US-5403228-$.DID. OR US-5405806-$.DID. OR US-5439551-$.DID. OR US-5449314-$.DID. OR US-5483568-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:24

S29	11	US-5321304-$.DID. OR US-5337015-$.DID. OR US-5362669-$.DID. OR US-5385866-$.DID. OR US-5389194-$.DID. OR US-5399234-$.DID. OR US-5403228-$.DID. OR US-5405806-$.DID. OR US-5439551-$.DID. OR US-5449314-$.DID. OR US-5483568-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:24
S28	11	US-5196353-$.DID. OR US-5222329-$.DID. OR US-5240522-$.DID. OR US-5245790-$.DID. OR US-5245794-$.DID. OR US-5258093-$.DID. OR US-5265378-$.DID. OR US-5271798-$.DID. OR US-5272115-$.DID. OR US-5308438-$.DID. OR US-5310455-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:24
S27	11	US-3734620-$.DID. OR US-3748014-$.DID. OR US-4312732-$.DID. OR US-4374915-$.DID. OR US-4632724-$.DID. OR US-4689491-$.DID. OR US-4793895-$.DID. OR US-5036015-$.DID. OR US-5081421-$.DID. OR US-5151584-$.DID. OR US-5169491-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:22
S26	1	"6247998".pn.	US-PGPUB; USPAT	OR	ON	2009/10/07 15:20
S25	6	US-2408764-$.DID. OR US-4745608-$.DID. OR US-6229272-$.DID. OR US-6248995-$.DID. OR US-6374053-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:18
S24	6	US-2408764-$.DID. OR US-4745608-$.DID. OR US-6229272-$.DID. OR US-6248995-$.DID. OR US-6374053-$.DID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:18
S23	3	S22 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:16
S22	1443	(imag$4 near5 (speed velocit $4) near5 (object substrate semiconductor wafer die) near5 (motion moving movement))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:13

S21	7	S17 and ((speed velocit$4) near5 (object substrate semiconductor wafer die) near5 (motion moving movement))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:11
S20	62	S17 and ((speed velocit$4) near5 (object substrate semiconductor wafer die))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:10
S19	29	S17 and ((speed velocit$4) near5 (object substrate))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:07
S18	105	S17 and ((speed velocit$4) same (image))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:06
S17	521	thick$5 same (CMP (chemical near2 mechanical near2 planarization)) same (imag$4)	US-PGPUB; USPAT	OR	ON	2009/10/07 14:05
S16	26169	thick$5 same (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:05

EAST Search History (Interference)

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10/12/09 9:48:10 AM
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